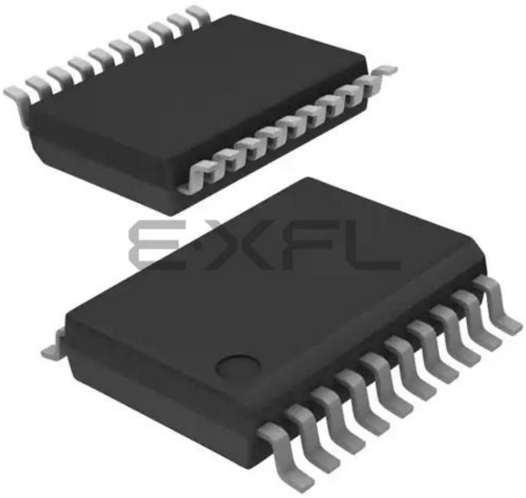
Microchip Technology - PIC16CE624-04E/SS Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16ce624-04e-ss

Table of Contents

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Corrections to this Data Sheet

We constantly strive to improve the quality of all our products and documentation. We have spent a great deal of time to ensure that this document is correct. However, we realize that we may have missed a few things. If you find any information that is missing or appears in error, please:

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NOTES:

4.2.2.6 PCON REGISTER

The PCON register contains flag bits to differentiate between a Power-on Reset, an external $\overline{\text{MCLR}}$ reset, WDT reset or a Brown-out Reset.

> **Note:** $\overline{\text{BOD}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOD}}$ is cleared, indicating a brown-out has occurred. The $\overline{\text{BOD}}$ status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by programming BODEN bit in the configuration word).

REGISTER 4-6: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOD}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR reset
-x = Unknown at POR reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{\text{POR}}$**: Power-on Reset Status bit
`1` = No Power-on Reset occurred
`0` = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{\text{BOD}}$**: Brown-out Reset Status bit
`1` = No Brown-out Reset occurred
`0` = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

4.4 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

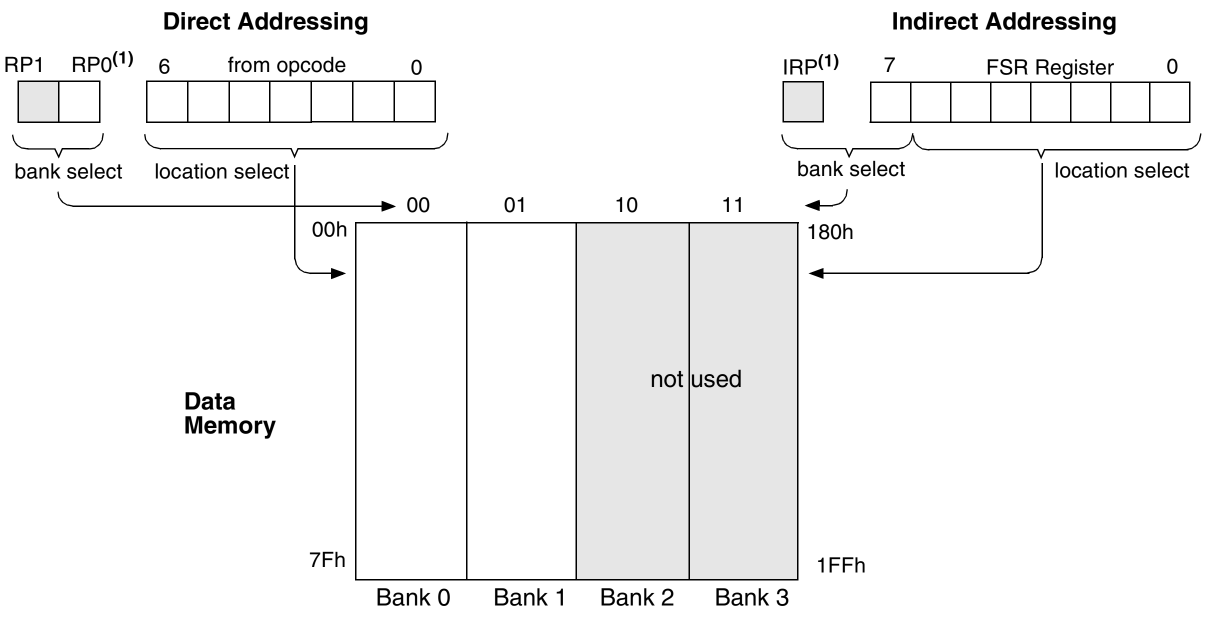
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the File Select Register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-7. However, IRP is not used in the PIC16CE62X.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 4-1.

EXAMPLE 4-1: INDIRECT ADDRESSING

```
          movlw   0x20     ;initialize pointer
          movwf   FSR      ;to RAM
NEXT      clrf    INDF     ;clear INDF register
          incf    FSR      ;inc pointer
          btfss   FSR,4    ;all done?
          goto    NEXT     ;no clear next
                           ;yes continue
CONTINUE:
```

FIGURE 4-7: DIRECT/INDIRECT ADDRESSING PIC16CE62X



For memory map detail see Figure 4-4 and Figure 4-5.

Note 1: The RP1 and IRP bits are reserved; always maintain these bits clear.

6.3 Write Operations

6.3.1 BYTE WRITE

Following the start signal from the processor, the device code (4 bits), the don't care bits (3 bits), and the $R/\overline{W}$ bit, which is a logic low, is placed onto the bus by the processor. This indicates to the EEPROM that a byte with a word address will follow after it has generated an acknowledge bit during the ninth clock cycle. Therefore, the next byte transmitted by the processor is the word address and will be written into the address pointer of the EEPROM. After receiving another acknowledge signal from the EEPROM, the processor will transmit the data word to be written into the addressed memory location. The EEPROM acknowledges again and the processor generates a stop condition. This initiates the internal write cycle, and during this time, the EEPROM will not generate acknowledge signals (Figure 6-5).

6.3.2 PAGE WRITE

The write control byte, word address and the first data byte are transmitted to the EEPROM in the same way as in a byte write. But instead of generating a stop condition, the processor transmits up to eight data bytes to the EEPROM, which are temporarily stored in the on-chip page buffer and will be written into the memory after the processor has transmitted a stop condition. After the receipt of each word, the three lower order address pointer bits are internally incremented by one. The higher order five bits of the word address remains constant. If the processor should transmit more than eight words prior to generating the stop condition, the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the stop condition is received, an internal write cycle will begin (Figure 6-6).

6.4 Acknowledge Polling

Since the EEPROM will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (this feature can be used to maximize bus throughput). Once the stop condition for a write command has been issued from the processor, the EEPROM initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the processor sending a start condition followed by the control byte for a write command ($R/\overline{W}$ = 0). If the device is still busy with the write cycle, then no ACK will be returned. If no ACK is returned, then the start bit and control byte must be re-sent. If the cycle is complete, then the device will return the ACK and the processor can then proceed with the next read or write command. See Figure 6-4 for flow diagram.

FIGURE 6-4: ACKNOWLEDGE POLLING FLOW

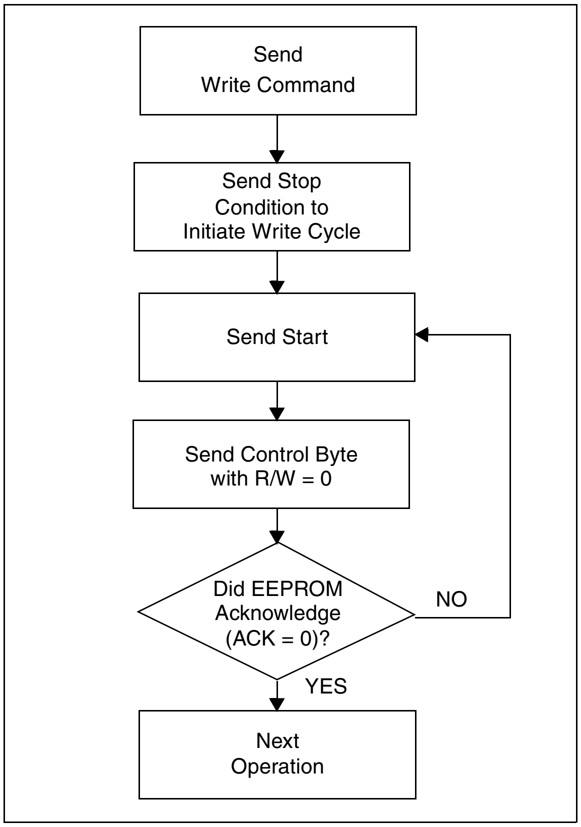
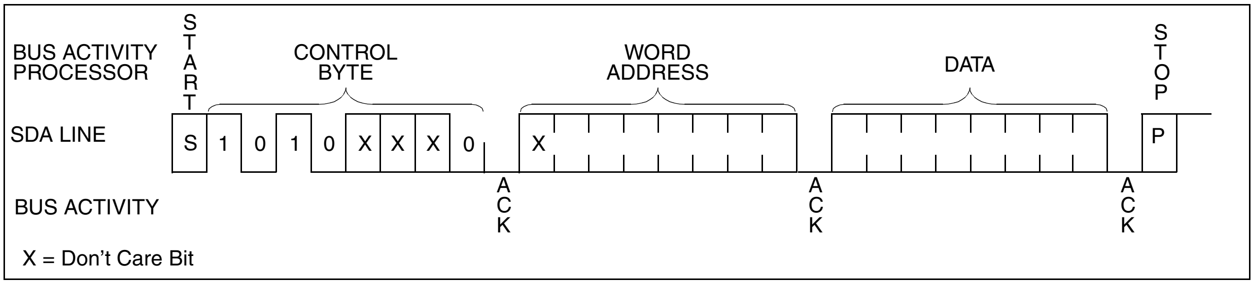


FIGURE 6-5: BYTE WRITE



8.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit, PIR1<6>, is the comparator interrupt flag. The CMIF bit must be reset by clearing ‘0’. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

> **Note:** If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<6>) interrupt flag may not get set.

The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of CMCON. This will end the mismatch condition.

b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition, and allow flag bit CMIF to be cleared.

8.7 Comparator Operation During SLEEP

When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake-up the device from SLEEP mode when enabled. While the comparator is powered-up, higher sleep currents than shown in the power down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM<2:0> = 111, before entering sleep. If the device wakes-up from sleep, the contents of the CMCON register are not affected.

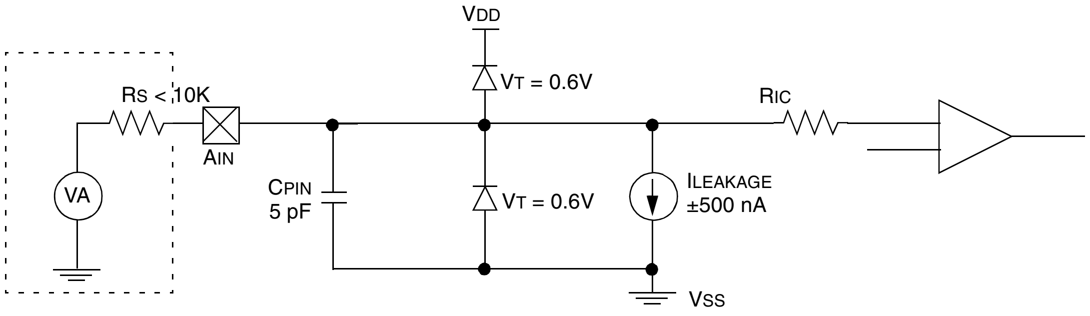
8.8 Effects of a RESET

A device reset forces the CMCON register to its reset state. This forces the comparator module to be in the comparator reset mode, CM<2:0> = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at reset time. The comparators will be powered-down during the reset interval.

8.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 8-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSS. The analog input therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 8-4: ANALOG INPUT MODEL



Legend
CPIN = Input capacitance
VT = Threshold voltage
ILEAKAGE = Leakage current at the pin due to various junctions
RIC = Interconnect resistance
RS = Source impedance
VA = Analog voltage

TABLE 8-1: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on All Other Resets
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	`00-- 0000`	`00-- 0000`
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	`000- 0000`	`000- 0000`
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	`0000 000x`	`0000 000u`
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	`-0-- ----`	`-0-- ----`
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	`-0-- ----`	`-0-- ----`
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	`---1 1111`	`---1 1111`

Legend: - = Unimplemented, read as "0", `x` = Unknown, `u` = unchanged

10.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance or one with parallel resonance.

Figure 10-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 10-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

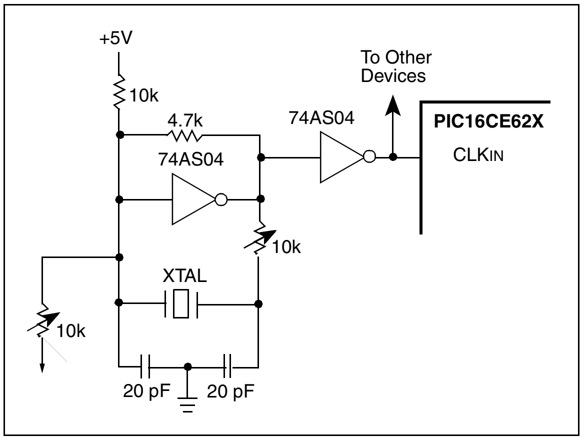
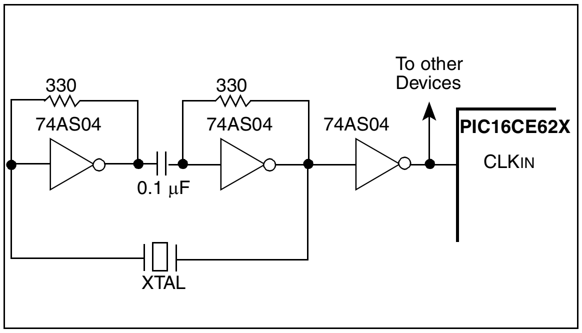


Figure 10-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 10-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



10.2.4 RC OSCILLATOR

For timing insensitive applications the “RC” device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 10-5 shows how the R/C combination is connected to the PIC16CE62X. For Rext values below 2.2 kΩ, the oscillator operation may become unstable, or stop completely. For very high Rext values (i.e., 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep Rext between 3 kΩ and 100 kΩ.

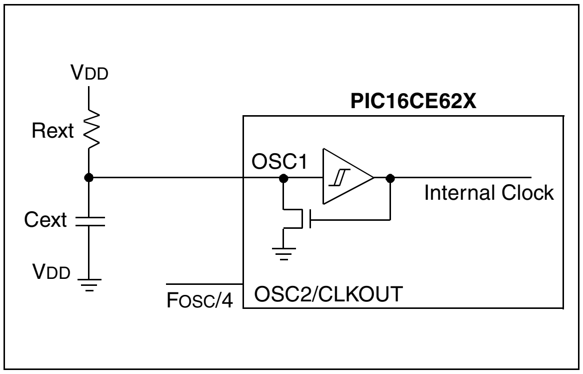
Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 14.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 14.0 for variation of oscillator frequency due to VDD for given Rext/Cext values, as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 10-5: RC OSCILLATOR MODE



10.4.5 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: First PWRT time-out is invoked after POR has expired, then OST is activated. The total time-out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in RC mode with $\overline{\text{PWRTE}}$ bit erased (PWRT disabled), there will be no time-out at all. Figure 10-8, Figure 10-9 and Figure 10-10 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 10-9). This is useful for testing purposes or to synchronize more than one PIC® device operating in parallel.

Table 10-5 shows the reset conditions for some special registers, while Table 10-6 shows the reset conditions for all the registers.

10.4.6 POWER CONTROL (PCON)/STATUS REGISTER

The power control/status register, PCON (address 8Eh) has two bits.

Bit0 is $\overline{\text{BOR}}$ (Brown-out). $\overline{\text{BOR}}$ is unknown on power-on-reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOR}}$ = 0 indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by setting BODEN bit = 0 in the Configuration word).

Bit1 is $\overline{\text{POR}}$ (Power-on-reset). It is a '0' on power-on-reset and unaffected otherwise. The user must write a '1' to this bit following a power-on-reset. On a subsequent reset, if $\overline{\text{POR}}$ is '0', it will indicate that a power-on-reset must have occurred (VDD may have gone too low).

TABLE 10-3: TIME-OUT IN VARIOUS SITUATIONS

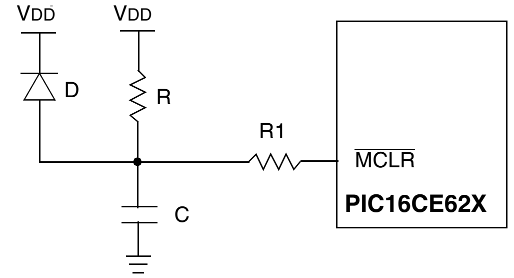
Oscillator Configuration	Power-up		Brown-out Reset	Wake-up from SLEEP
	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1		
XT, HS, LP	72 ms + 1024 TOSC	1024 TOSC	72 ms + 1024 TOSC	1024 TOSC
RC	72 ms	—	72 ms	—

TABLE 10-4: STATUS/PCON BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	
0	X	1	1	Power-on-reset
0	X	0	X	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	X	X	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
1	0	X	X	Brown-out Reset
1	1	0	u	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{\text{MCLR}}$ reset during normal operation
1	1	1	0	$\overline{\text{MCLR}}$ reset during SLEEP

Legend: `x` = unknown, `u` = unchanged

FIGURE 10-11: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

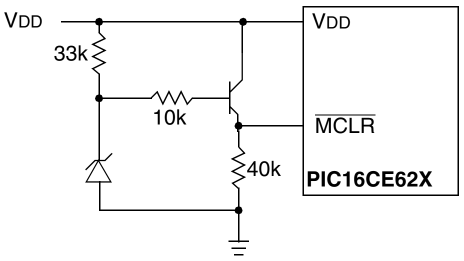


Note 1: External power-on reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into $\overline{\text{MCLR}}$ from external capacitor C in the event of $\overline{\text{MCLR}}$/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

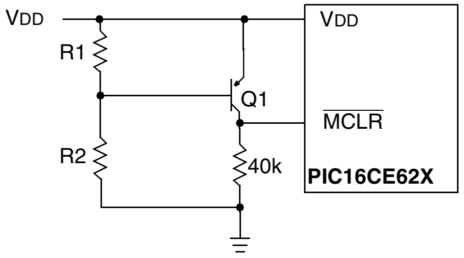
FIGURE 10-12: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1



Note 1: This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

2: Internal Brown-out Reset circuitry should be disabled when using this circuit.

FIGURE 10-13: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



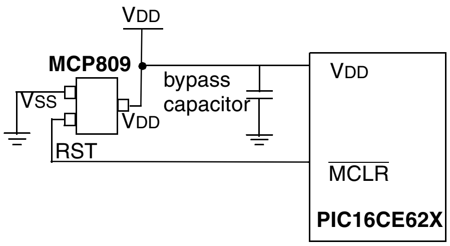
Note 1: This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \times \frac{R1}{R1 + R2} = 0.7\text{ V}$$

2: Internal brown-out detection should be disabled when using this circuit.

3: Resistors should be adjusted for the characteristics of the transistor.

FIGURE 10-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3



This brown-out protection circuit employs Microchip Technology's MCP809 microcontroller supervisor. The MCP8XX and MCP1XX families of supervisors provide push-pull and open collector outputs with both high and low active reset pins. There are 7 different trip point selections to accommodate 5V and 3V systems.

10.5 Interrupts

The PIC16CE62X has 4 sources of interrupt:

- External interrupt RB0/INT
- TMR0 overflow interrupt
- PortB change interrupts (pins RB<7:4>)
- Comparator interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. GIE is cleared on reset.

The “return from interrupt” instruction, `RETFIE`, exits interrupt routine, as well as sets the GIE bit, which re-enable RB0/INT interrupts.

The INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flag is contained in the special register PIR1. The corresponding interrupt enable bit is contained in special registers PIE1.

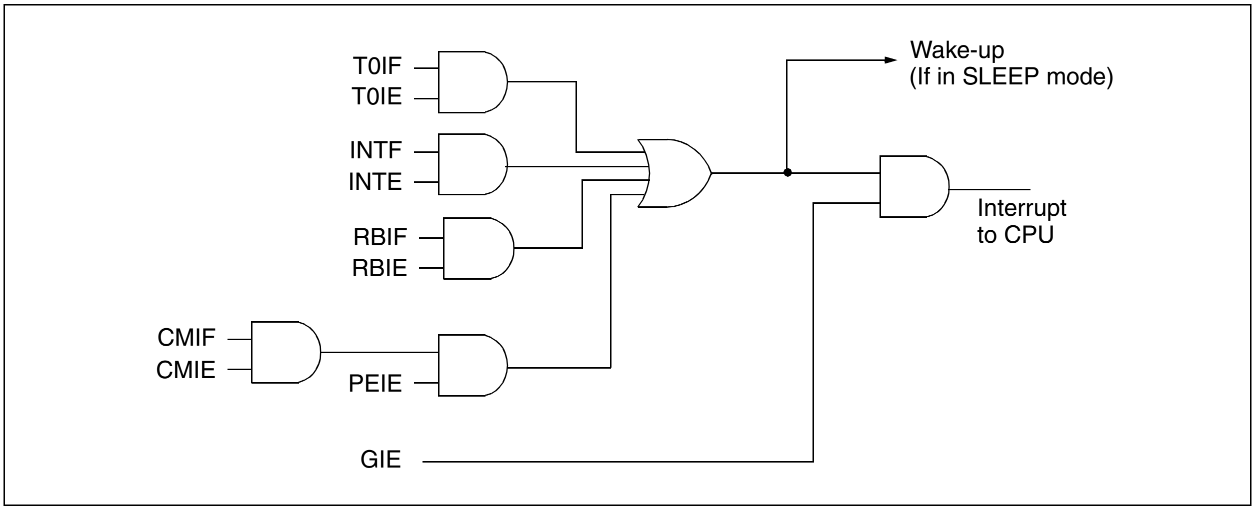
When an interrupt is responded to, the GIE is cleared to disable any further interrupt, the return address is pushed into the stack and the PC is loaded with 0004h. Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid RB0/INT recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends on when the interrupt event occurs (Figure 10-16). The latency is the same for one or two cycle instructions. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests.

Note 1: Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit or the GIE bit.

2: When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The CPU will execute a `NOP` in the cycle immediately following the instruction which clears the GIE bit. The interrupts which were ignored are still pending to be serviced when the GIE bit is set again.

FIGURE 10-15: INTERRUPT LOGIC



BCF Bit Clear f

Syntax: [*label*] BCF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $0 \rightarrow (f<b>)$

Status Affected: None

Encoding:

`01`	`00bb`	`bfff`	`ffff`

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Example

```
BCF     FLAG_REG, 7
```

Before Instruction
FLAG_REG = 0xC7
After Instruction
FLAG_REG = 0x47

BSF Bit Set f

Syntax: [*label*] BSF f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: $1 \rightarrow (f<b>)$

Status Affected: None

Encoding:

`01`	`01bb`	`bfff`	`ffff`

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Example

```
BSF    FLAG_REG,   7
```

Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

BTFSC Bit Test, Skip if Clear

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 127$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

`01`	`10bb`	`bfff`	`ffff`

Description: If bit 'b' in register 'f' is '0', then the next instruction is skipped.
If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded, and a `NOP` is executed instead, making this a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```
HERE    BTFSC  FLAG,1
FALSE   GOTO   PROCESS_CODE
TRUE    •
        •
        •
```

Before Instruction
PC = address `HERE`
After Instruction
if FLAG<1> = 0,
PC = address `TRUE`
if FLAG<1>=1,
PC = address `FALSE`

IORWF Inclusive OR W with f

Syntax:	[*label*] IORWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(W) .OR. (f) → (dest)
Status Affected:	Z
Encoding:	`00` `0100` `dfff` `ffff`
Description:	Inclusive OR the W register with register 'f'. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
Words:	1
Cycles:	1
Example	`IORWF RESULT, 0` Before Instruction RESULT = 0x13 W = 0x91 After Instruction RESULT = 0x13 W = 0x93 Z = 1

MOVLW Move Literal to W

Syntax:	[*label*] MOVLW k
Operands:	0 ≤ k ≤ 255
Operation:	k → (W)
Status Affected:	None
Encoding:	`11` `00xx` `kkkk` `kkkk`
Description:	The eight bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.
Words:	1
Cycles:	1
Example	`MOVLW 0x5A` After Instruction W = 0x5A

MOVF Move f

Syntax:	[*label*] MOVF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f) → (dest)
Status Affected:	Z
Encoding:	`00` `1000` `dfff` `ffff`
Description:	The contents of register f are moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.
Words:	1
Cycles:	1
Example	`MOVF FSR, 0` After Instruction W = value in FSR register Z = 1

MOVWF Move W to f

Syntax:	[*label*] MOVWF f
Operands:	0 ≤ f ≤ 127
Operation:	(W) → (f)
Status Affected:	None
Encoding:	`00` `0000` `1fff` `ffff`
Description:	Move data from W register to register 'f'.
Words:	1
Cycles:	1
Example	`MOVWF OPTION` Before Instruction OPTION = 0xFF W = 0x4F After Instruction OPTION = 0x4F W = 0x4F

NOP No Operation

Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Encoding:	`00 0000 0xx0 0000`
Description:	No operation.
Words:	1
Cycles:	1
Example	`NOP`

OPTION Load Option Register

Syntax:	[*label*] OPTION
Operands:	None
Operation:	(W) → OPTION
Status Affected:	None
Encoding:	`00 0000 0110 0010`
Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.
Words:	1
Cycles:	1
Example	

To maintain upward compatibility with future PIC® MCU products, do not use this instruction.

RETFIE Return from Interrupt

Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None
Encoding:	`00 0000 0000 1001`
Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction.
Words:	1
Cycles:	2
Example	`RETFIE`

After Interrupt

PC = TOS

GIE = 1

RETLW Return with Literal in W

Syntax:	[*label*] RETLW k
Operands:	$0 \le k \le 255$
Operation:	k → (W); TOS → PC
Status Affected:	None
Encoding:	`11 01xx kkkk kkkk`
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.
Words:	1
Cycles:	2

Example

```
        CALL TABLE    ;W contains table
                      ;offset value
        •             ;W now has table
        value
        •
TABLE   •
        ADDWF PC      ;W = offset
        RETLW k1      ;Begin table
        RETLW k2      ;
        •
        •
        •
        RETLW kn      ; End of table
```

Before Instruction

W = 0x07

After Instruction

W = value of k8

TABLE 12-1: DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	24CXX/ 25CXX/ 93CXX	HCSXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	MPLAB® C17 Compiler												✓	✓					
	MPLAB® C18 Compiler														✓				
	MPASM/MPLINK	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Emulators	MPLAB®-ICE	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓				
	PICMASTER/PICMASTER-CE	✓	✓	✓	✓	✓		✓	✓	✓		✓	✓	✓					
	ICEPIC™ Low-Cost In-Circuit Emulator	✓		✓	✓	✓		✓	✓	✓		✓							
Debugger	MPLAB®-ICD In-Circuit Debugger				✓*			✓*			✓								
Programmers	PICSTART®Plus Low-Cost Universal Dev. Kit	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓				
	PRO MATE® II Universal Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	SIMICE	✓		✓															
	PICDEM-1			✓		✓		✓†		✓			✓						
	PICDEM-2				✓†			✓†							✓				
	PICDEM-3											✓							
	PICDEM-14A		✓																
	PICDEM-17													✓					
	KEELOQ® Evaluation Kit																✓		
	KEELOQ Transponder Kit																✓		
	microID™ Programmer's Kit																	✓	
	125 kHz microID Developer's Kit																	✓	
	125 kHz Anticollision microID Developer's Kit																	✓	
	13.56 MHz Anticollision microID Developer's Kit																	✓	
	MCP2510 CAN Developer's Kit																		✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB®-ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77

** Contact Microchip Technology Inc. for availability date.

† Development tool is available on select devices.

13.3 DC CHARACTERISTICS: PIC16CE62X-04 (Commercial, Industrial, Extended) PIC16CE62X-20 (Commercial, Industrial, Extended) PIC16LCE62X (Commercial, Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise stated)** Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range as described in DC spec Table 13-1				
Parm No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Unit**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	VSS	–	0.8V 0.15VDD	V	VDD = 4.5V to 5.5V, Otherwise
D031		with Schmitt Trigger input	VSS		0.2VDD	V	
D032		$\overline{\text{MCLR}}$, RA4/T0CKI,OSC1 (in RC mode)	VSS	–	0.2VDD	V	Note1
D033		OSC1 (in XT and HS)	VSS	–	0.3VDD	V	
		OSC1 (in LP)	VSS	–	0.6VDD - 1.0	V	
	VIH	**Input High Voltage**					
		I/O ports					
D040		with TTL buffer	2.0V .25VDD + 0.8V	–	VDD VDD	V	VDD = 4.5V to 5.5V, Otherwise
D041		with Schmitt Trigger input	0.8VDD		VDD		
D042		$\overline{\text{MCLR}}$ RA4/T0CKI	0.8VDD	–	VDD	V	
D043		OSC1 (XT, HS and LP)	0.7VDD	–	VDD	V	
D043A		OSC1 (in RC mode)	0.9VDD				Note1
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	VDD = 5.0V, VPIN = VSS
		Input Leakage Current					
	IIL	(Notes 2, 3)					
		I/O ports (Except PORTA)			±1.0	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	–	–	±0.5	μA	Vss ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	–	–	±1.0	μA	Vss ≤ VPIN ≤ VDD
D063		OSC1, $\overline{\text{MCLR}}$	–	–	±5.0	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	VOL	**Output Low Voltage**					
D080		I/O ports	–	–	0.6	V	IOL=8.5 mA, VDD=4.5V, -40° to +85°C
			–	–	0.6	V	IOL=7.0 mA, VDD=4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	–	–	0.6	V	IOL=1.6 mA, VDD=4.5V, -40° to +85°C
			–	–	0.6	V	IOL=1.2 mA, VDD=4.5V, +125°C
	VOH	**Output High Voltage** (Note 3)					
D090		I/O ports (Except RA4)	VDD-0.7	–	–	V	IOH=-3.0 mA, VDD=4.5V, -40° to +85°C
			VDD-0.7	–	–	V	IOH=-2.5 mA, VDD=4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	–	–	V	IOH=-1.3 mA, VDD=4.5V, -40° to +85°C
			VDD-0.7	–	–	V	IOH=-1.0 mA, VDD=4.5V, +125°C
*D150	VOD	**Open-Drain High Voltage**			8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	Cio	All I/O pins/OSC2 (in RC mode)			50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16CE62X be driven with external clock in RC mode.

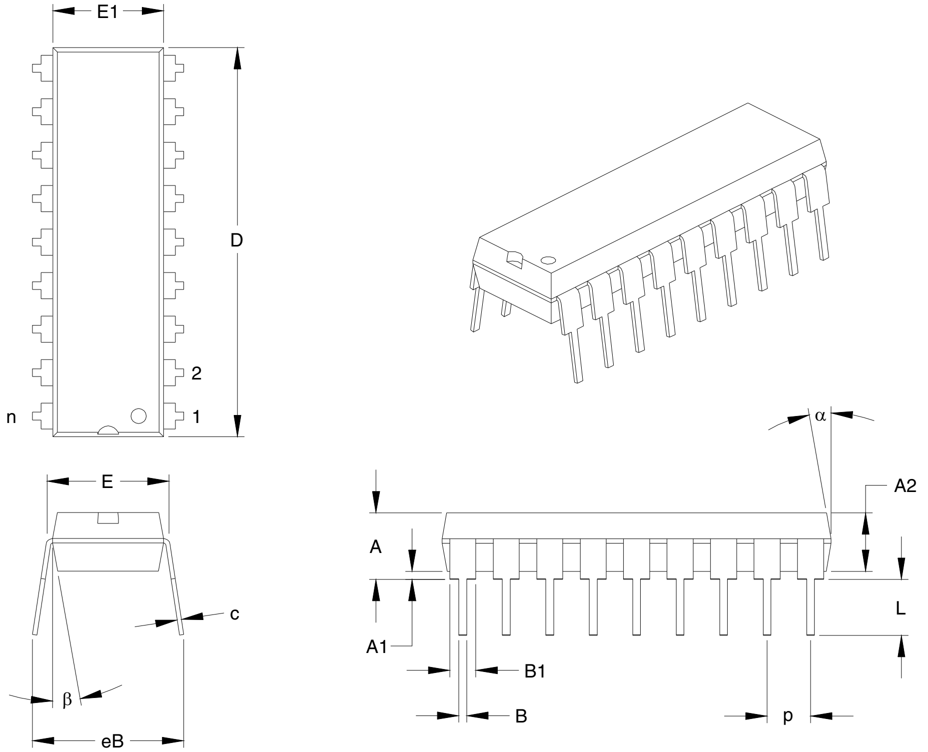
2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

NOTES:

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

*Controlling Parameter

Notes:

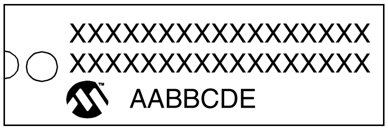
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.

JEDEC Equivalent: MS-001

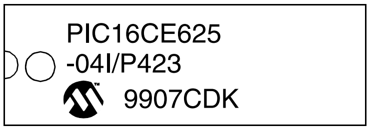
Drawing No. C04-007

14.1 Package Marking Information

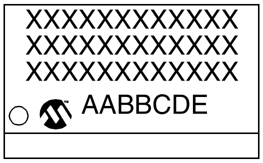
18-Lead PDIP



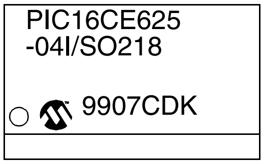
Example



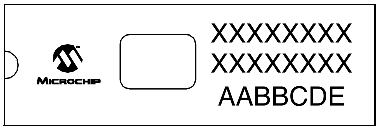
18-Lead SOIC (.300")



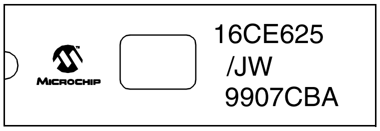
Example



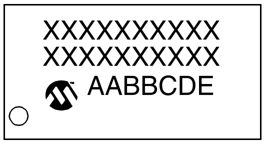
18-Lead CERDIP Windowed



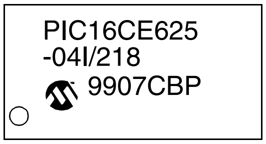
Example



20-Lead SSOP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

NOTES: